**Product / Process Change Notice**

**Parts Affected:**

The following Schottky and Ultra-Fast Recovery Rectifiers manufactured in the D2PAK case:

CSHDD8-40

CSHDD8-60

CSHDD8-100

CSHDD16-40C

CSHDD16-60C

CSHDD16-100C

CSHDD16-200C

CUDD8-02

CUDD8-04

CUDD8-08

CUDD16-02C

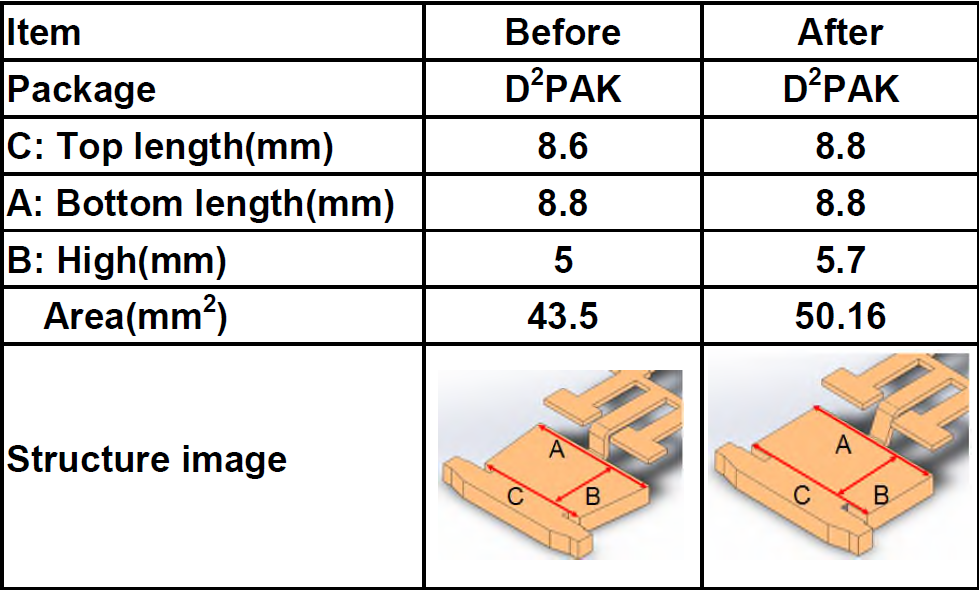
CUDD16-04C

CUDD16-06C

CUDD16-08C

**Extent of Change:**

The die attach pad size of the D2PAK has increased by 15%; refer to data below.



**Reason for Change:**

The purpose of the change is to enhance the heat dissipation capabilities of the D2PAK package.

**Effect of Change:**

This change does not affect the electrical characteristics of the product.

**Qualification:**

Standard evaluation and qualifications completed resulting in no performance

differences compared to current product.

**Effective Date of Change:**

Existing inventory will be shipped until depleted.

**Sample Availability:**

Please contact your salesperson or manufacturer’s representative for samples.

As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor’s Product/Process Change Notification (PCN).

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| Company Name: |  |
| Address: |  |
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| Printed Name: |  |
| Title: |  |
| Signature: |  |
| Date: |  |